

# Funcionalization of Si by ionimplantation:

Influence on the tribomechanical and wettability properties at the micro and nano scales

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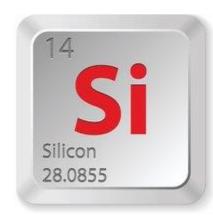
Encontro 2018 NanoLab/BioMat

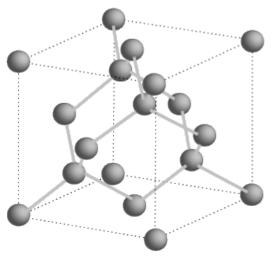
### Outline

- Introduction
  - Motivation/objective
- Experimental Conditions
- Resultas & discussion
- Conclusions

### Introduction

#### Why Silicon???





Transistor – electronic revolution in th 60's

2D electronics – IC's





3D devices – MEMS

### Introduction

#### Microelectromechanical System (MEMS)

- Devices with a 100 nm < L < 1 mm.
- Produced using IC's technologies.

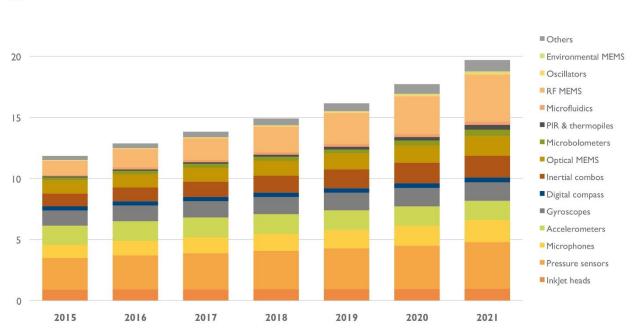




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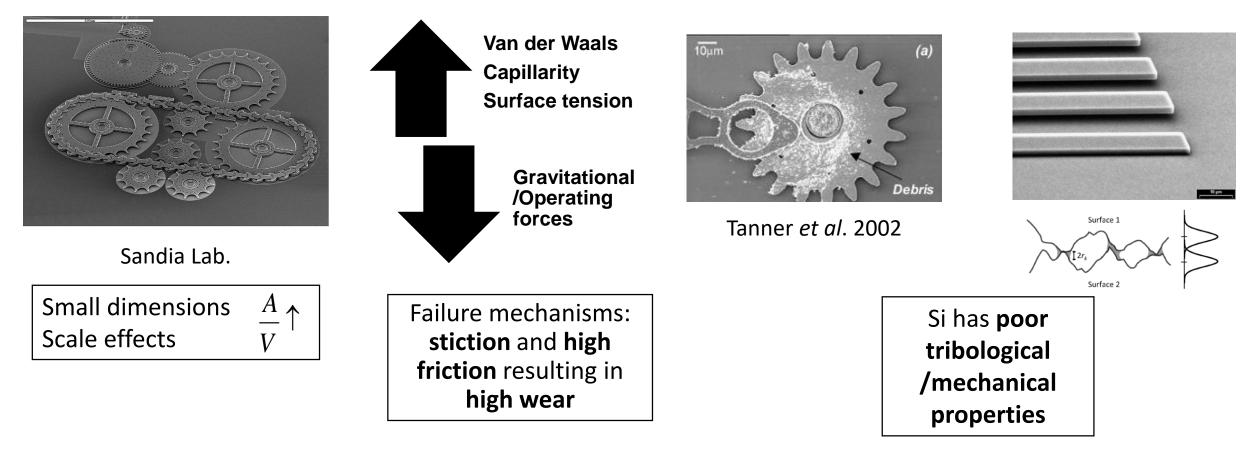
#### 2015-2021 MEMS market forecast in US\$B

(Source: Status of the MEMS Industry report, Yole Développement, May 2016)



## Objective

#### • Commercial MEMS do not have rubbing and impacting surfaces



Enhance the tribomechanical and wettability properties of Si using Ion-implantation.

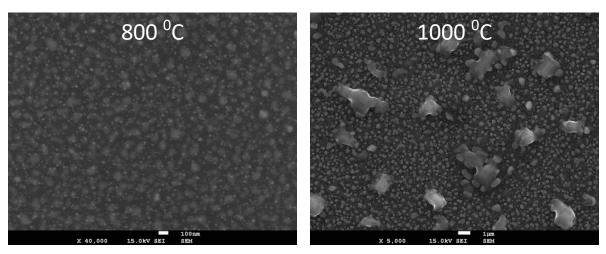
### **Experimental Conditions**

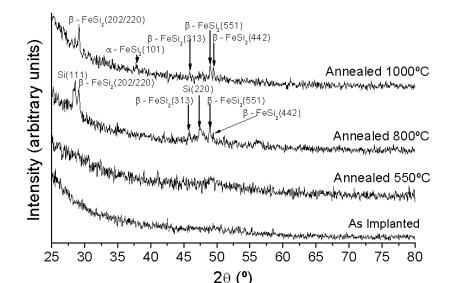
| Туре                        | Element (Energy<br>kev)                | Fluence<br>(cm <sup>-2</sup> )  | Conditions                                      | Annealings<br>( <sup>0</sup> C) |  |
|-----------------------------|--|---|---|---------------------------------|--|
| Single                      | Fe (150)<br>C (25)                     | (low) 5x10 <sup>15</sup><br>(medium) 5x10 <sup>16</sup><br>(high) 2x10 <sup>17</sup>                              | Room<br>temperature<br>&<br>normal<br>incidence | 550<br>800<br>1000              |  |
| Dual                        | Fe (170) + C (50)<br>Ti (160) + C (50) | ( <b>low</b> ) 5x10 <sup>16</sup> + 5x10 <sup>16</sup><br>( <b>high</b> ) 2x10 <sup>17</sup> + 2x10 <sup>17</sup> |   | 800<br>1000                     |  |
| Characterization Techniques |  |   |   |                                 |  |

| Characterization Techniques      |
|----------------------------------|
| FEG-SEM/AFM                      |
| GIRXD ( $\theta = 1.5^{\circ}$ ) |
| RBS/XPS                          |
| Wettability                      |
| Ultramicro hardness              |
| AFM-based Nanowear               |

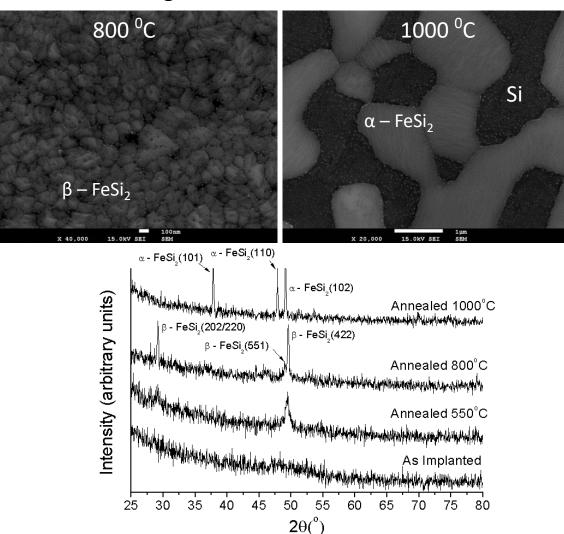
#### Results & Discussion – Fe<sup>+</sup> Implantation

Medium Fluence  $\Phi = 5 \times 10^{16} \text{ cm}^{-2}$ 



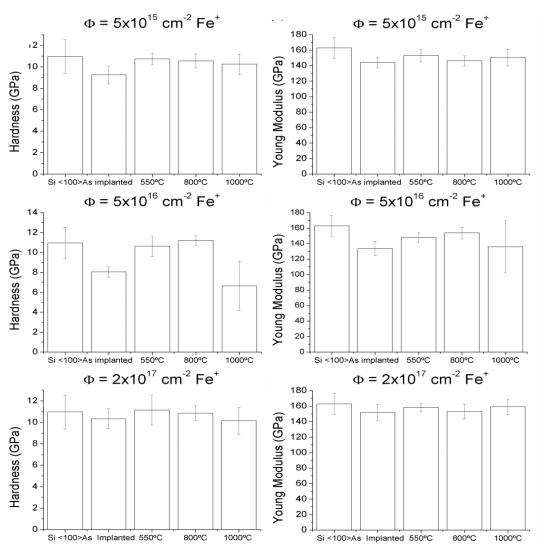


High Fluence  $\Phi = 2 \times 10^{17} \text{ cm}^{-2}$ 

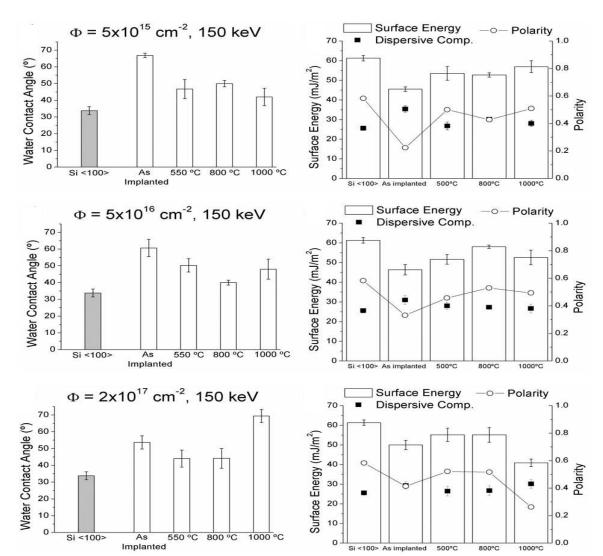


### Results & Discussion – Fe<sup>+</sup> Implantation

#### Ultramicrohardness (5 mN)

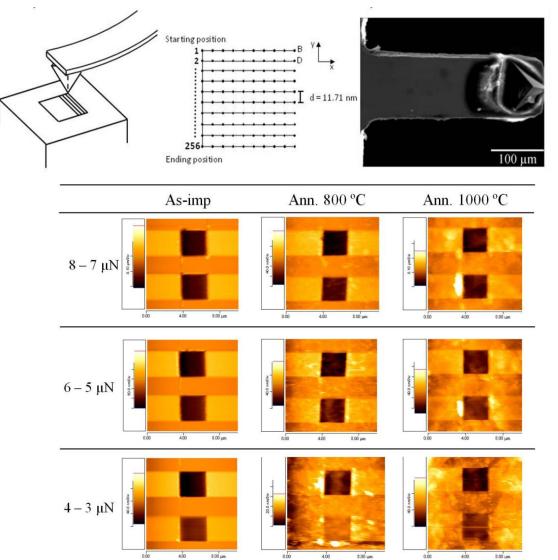


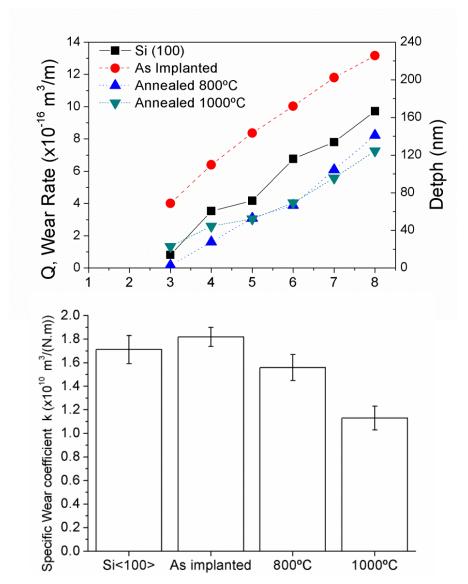
#### Contact angle and Surf. Energy



### Results & Discussion – Fe<sup>+</sup> Implantation

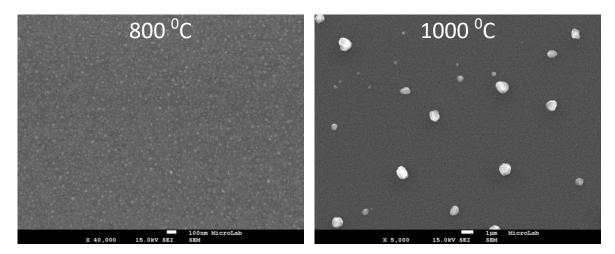
#### **AFM-based Nanowear**

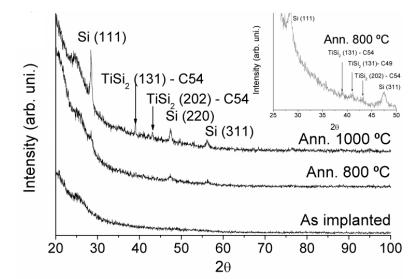




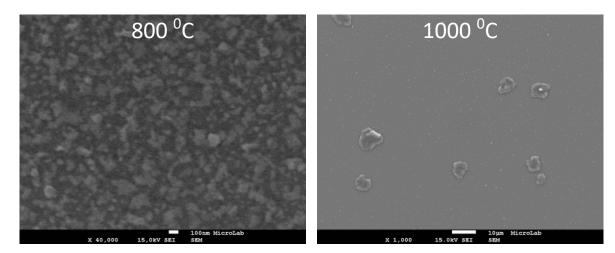
#### Results & Discussion – Ti<sup>+</sup> + C<sup>+</sup> Implantation

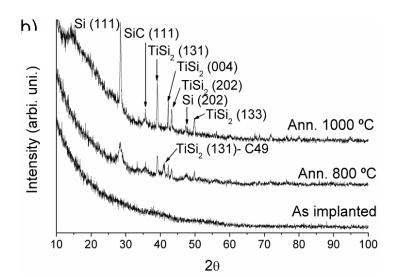
Medium Fluence  $\Phi = 5 \times 10^{16} \text{ cm}^{-2}$ 





High Fluence  $\Phi = 2 \times 10^{17}$  cm<sup>-2</sup>





### Results & Discussion – Ti<sup>+</sup> + C<sup>+</sup> Implantation

1.0

0.8

0.6

0.4

0.2

0.0

<sub>7</sub>1.0

0.8

0.6

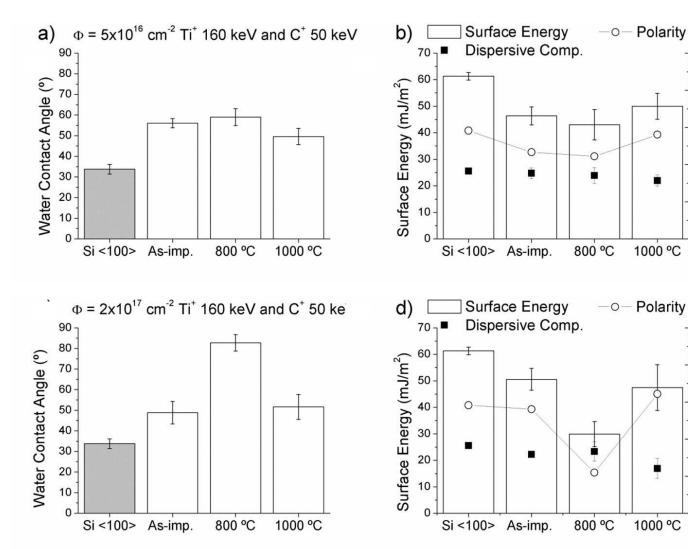
0.4

0.2

0.0

Polarity

Polarity



#### Low fluence

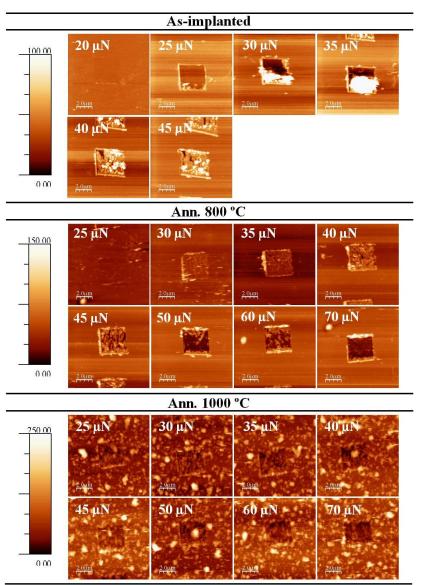
Identical values of  $\theta$  even after the annealings

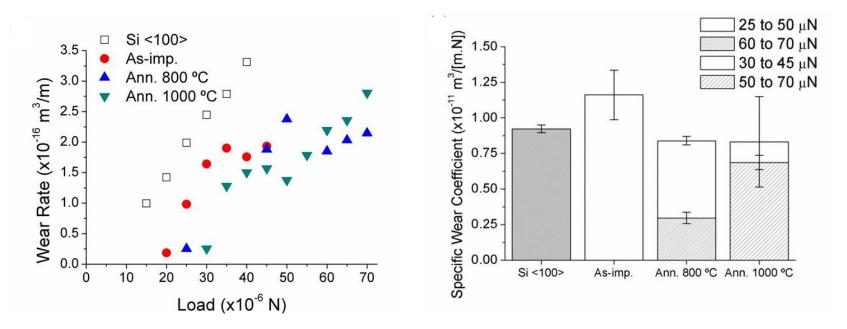
#### high fluence

The implanted and annealed samples present  $> \theta$ .

The 800 <sup>o</sup>C sample presented the higher contact angle.

### Results & Discussion – Ti+ + C+ Implantation





Almost all the calculated Q's are below the Si

The combination of TiSi<sub>2</sub> and SiC greatly improve the nanowear resistance.

The lowest **k** was calculated for the 800 <sup>0</sup>C for the higher loads

### Conclusions

- Wettability and Nanowear properties of Si can be upgraded using ionimplantation.
- From all the studied systems
  - The dual systems performed better than the single ones.
  - The singe C+ revealed the poorest performance.
  - Low fluence Fe++ C+ at 800 0C presented an almost hydrophobic behavior.
  - The Ti++C+ system at 800 0C combine both high angle contact angle and low average specific wear coefficient.